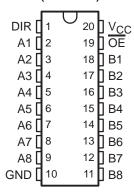
- B-Port Outputs Have Equivalent 25-Ω
 Series Resistors, So No External Resistors
 Are Required
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds 2000 V Per MIL-STD-833, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Impedance State During Power Up and Power Down
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package

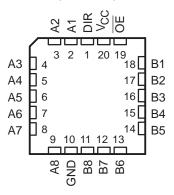
description

These octal transceivers and line drivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are effectively isolated.

SN54ABT2245 . . . J OR W PACKAGE SN74ABT2245 . . . DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT2245 . . . FK PACKAGE (TOP VIEW)



The B-port outputs, which are designed to sink up to 12 mA, include equivalent $25-\Omega$ series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN54ABT2245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT2245 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INP	UTS	OPERATION				
OE	DIR	OPERATION				
L	L	B data to A bus				
L	Н	A data to B bus				
Н	X	Isolation				

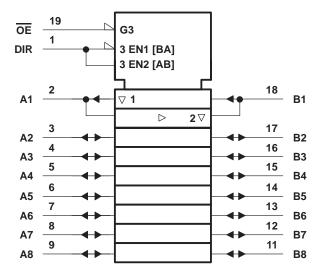


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

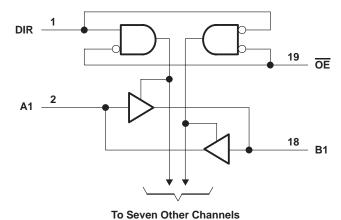
TEXAS INSTRUMENTS
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logic symbol†



 $[\]ensuremath{^{\dagger}}$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

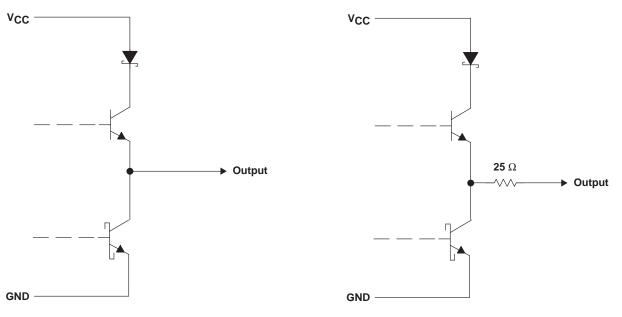
logic diagram (positive logic)





schematic of A-port outputs

schematic of B-port outputs



All resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Voltage range applied to any output in the high or power-off state, V _O	
Current into any output in the low state, I_0 : SN54ABT2245 (except B port)	
SN74ABT2245 (except B port)	
B port	
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DB package	115°C/W
DW package	97°C/W
N package	67°C/W
PW package	128°C/W
Storage temperature range, T _{stq} –	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



SN54ABT2245, SN74ABT2245 OCTAL TRANSCEIVERS AND LINE/MOS DRIVERS WITH 3-STATE OUTPUTS SCBS234D – SEPTEMBER 1992 – REVISED MAY 1997

recommended operating conditions (see Note 3)

			SN54AE	3T2245	SN74AB	T2245	UNIT	
			MIN	MAX	MIN	MAX	UNIT	
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage		2		2		V	
VIL	Low-level input voltage			0.8		0.8	V	
VI	Input voltage		0	VCC	0	VCC	V	
lou	High-level output current	A port		-24		-32	mA	
ІОН	riigh-level output current	B port		-12		-12		
la.	Low-level output current	A port		48		64	mA	
IOL	Low-level output current	B port		12		12	.] '''A	
Δt/Δν	Input transition rise or fall rate	Outputs enabled		5		5	ns/V	
Δt/ΔVCC	Power-up ramp rate		200		200		μs/V	
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONF	T,	Δ = 25°C	;	SN54AE	T2245	SN74ABT2245		UNIT		
PAI	RAMETER	TEST CONE	DITIONS	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	3.35			3.3		3.35			
	D nort	$V_{CC} = 5 V$,	$I_{OH} = -1 \text{ mA}$	3.85			3.8		3.85			
	B port	V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$				3		3.1			
\/-··		VCC = 4.5 V	I _{OH} = -12 mA	2.6					2.6		V	
VOH		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		V	
	A nort	$V_{CC} = 5 V$,	I _{OH} = -3 mA	3			3		3			
	A port	V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2					
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
	5 .		$I_{OL} = 8 \text{ mA}$			0.65		0.8		0.65		
\/a:	B port	V00 - 4 5 V	I _{OL} = 12 mA			0.8				0.8	V	
VOL	A most	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
	A port		I _{OL} = 64 mA			0.55*				0.55		
V _{hys}					100						mV	
	Control inputs $V_{CC} = 0$ to 5.5 V, $V_{I} = 0$		V _{CC} or GND			±1		±1		±1		
ΙĮ	A or B ports	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$ $V_{I} = V_{CC} \text{ or GND}$			±20			±20		±20	μΑ	
l _{OZH} ‡		$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$ $V_{O} = 2.7 \text{ V}, \overline{OE} \ge 2 \text{ V}$ 10			10	μΑ						
lozL‡		$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$ $V_{O} = 0.5 \text{ V}, \overline{OE} \ge 2 \text{ V}$				-10		-10		-10	μΑ	
lozpu§	}	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \overline{O}$	Ē = X			±50		±50		±50	μА	
IOZPD	}	$V_{CC} = 2.1 \text{ V to } 0,$ $V_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \overline{0}$				±50		±50		±50	μΑ	
l _{off}		V _{CC} = 0,	V _I or V _O ≤ 4.5 V			±100				±100	μΑ	
ICEX	Outputs high	V _{CC} = 5.5 V,	V _O = 5.5 V			50		50		50	μΑ	
	B port			-25	-	-100	-25	-100	-25	-100	· ·	
IO¶	A port	V _{CC} = 5.5 V,	$V_0 = 2.5 \text{ V}$	-50	-100	-180	-50	-180	-50	-180	mA	
		V 55V	Outputs high		1	250		250		250	μΑ	
Icc	A or B ports	$V_{CC} = 5.5 \text{ V},$ $I_{C} = 0,$	Outputs low		24	32		32		32	mA	
	'	$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μΑ	
		V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5		
ΔlCC#	Data inputs	Other inputs at V _{CC} or GND	Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs	V _{CC} = 5.5 V, One inputous of the original origina				1.5		1.5		1.5		
C _i	-	V _I = 2.5 V or 0.5 V			3						pF	
C _{io}		V _O = 2.5 V or 0.5 V			6						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] This parameter is characterized but not production tested.

 $[\]P$ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

SN54ABT2245, SN74ABT2245 OCTAL TRANSCEIVERS AND LINE/MOS DRIVERS WITH 3-STATE OUTPUTS

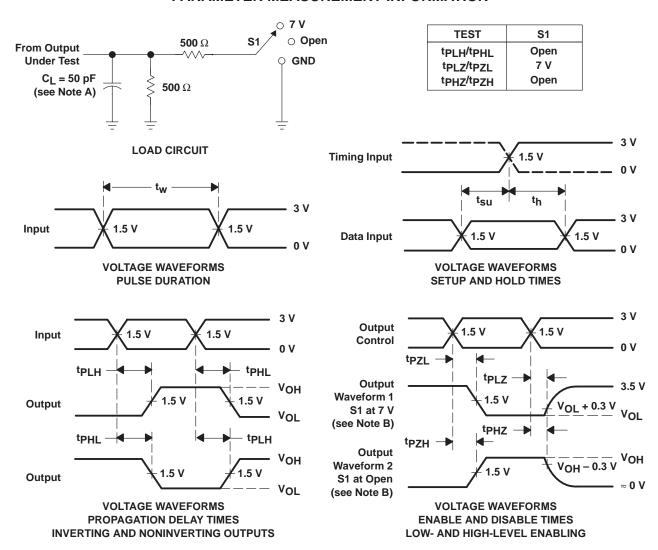
SCBS234D - SEPTEMBER 1992 - REVISED MAY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	/, ;	SN54AB	T2245	SN74AB	UNIT		
	(1141 01)		MIN	TYP	MAX	MIN	MAX	MIN	MAX		
^t PLH	А	В	1	2.5	3.4	1	4	1	3.8	ns	
^t PHL	^	Ь	1	3.2	4.2	1	4.6	1	4.5	115	
^t PLH	В	А	1	2.2	3.2	1	3.8	1	3.6	20	
^t PHL	В	A	1	2.7	3.6	1	4.2	1	4	ns	
^t PZH	ŌĒ	А	1	3.3	4.6	1	5.6	1	5.5	ns	
t _{PZL}	OE OE	A	1	3.2	4.7	1	6	1	5.7	115	
^t PHZ	ŌĒ	А	2	4	5.1	2	5.7	2	5.6	20	
t _{PLZ}		A	1	2.9	4	1	4.6	1	4.5	ns	
^t PZH		D	1.5	3.6	4.9	1.5	6.3	1.5	6.1		
t _{PZL}	ŌĒ	В	1.5	3.9	5.3	1.5	6.6	1.5	6.3	ns	
^t PHZ		В	1.5	3.6	4.7	1.5	5.5	1.5	5.3		
^t PLZ	ŌĒ	В	1.5	3.3	4.4	1.5	4.9	1.5	4.8	ns	



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq 2.5 \ ns$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





25-Sep-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
5962-9560601Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9560601Q2A SNJ54 ABT2245FK	Samples
5962-9560601QRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9560601QR A SNJ54ABT2245J	Samples
5962-9560601QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9560601QS A SNJ54ABT2245W	Samples
SN74ABT2245DBLE	OBSOLETE	E SSOP	DB	20		TBD	Call TI	Call TI	-40 to 85		
SN74ABT2245DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SN74ABT2245DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SN74ABT2245DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples
SN74ABT2245DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples
SN74ABT2245DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples
SN74ABT2245DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples
SN74ABT2245DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples
SN74ABT2245DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples
SN74ABT2245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT2245N	Samples
SN74ABT2245NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT2245N	Samples
SN74ABT2245NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples
SN74ABT2245NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
SN74ABT2245NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2245	Samples
SN74ABT2245PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SN74ABT2245PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SN74ABT2245PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SN74ABT2245PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 85		
SN74ABT2245PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SN74ABT2245PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SN74ABT2245PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AA245	Samples
SNJ54ABT2245FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9560601Q2A SNJ54 ABT2245FK	Samples
SNJ54ABT2245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9560601QR A SNJ54ABT2245J	Samples
SNJ54ABT2245W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9560601QS A SNJ54ABT2245W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

25-Sep-2013

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54ABT2245, SN74ABT2245:

Catalog: SN74ABT2245

Military: SN54ABT2245

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All differsions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT2245DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT2245DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ABT2245NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ABT2245PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT2245DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ABT2245DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ABT2245NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ABT2245PWR	TSSOP	PW	20	2000	367.0	367.0	38.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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